1.5±0.1

0.4±0.04

Base Collector 3: Emitter MiniP3-F1 Package

 $1.0^{+0.25}_{-0.20}$ 2.5±0.

4.5+0

.6±0.

Unit: mm

# **2SB1440**

## Silicon PNP epitaxial planar type

For low-frequency output amplification Complementary to 2SD2185

#### Features

4

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	. <u>3,0±0.15</u>
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-50	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-50	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	-5	V	
Collector current	I <sub>C</sub>	-2	Α	
Peak collector current	I <sub>CP</sub>	-3	A	Marking Symbol: 14
Collector power dissipation *	P <sub>C</sub>	1	W	S'
Junction temperature	Tj	150	°C	ate of
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

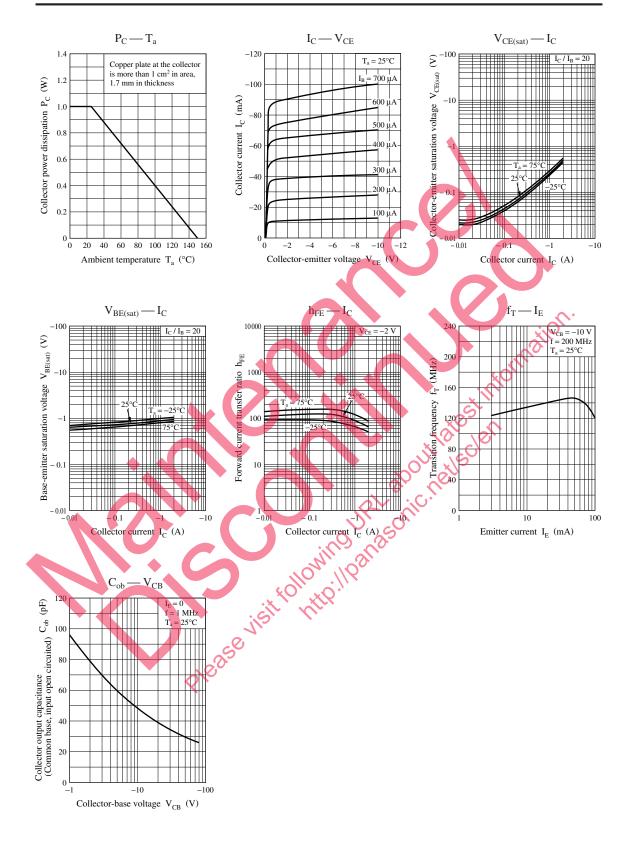
Collector current	I <sub>C</sub>	-2 A		C)				
Peak collector current	I <sub>CP</sub>	-2 A Marking S	Symbol	- Ale				
Collector power dissipation *	P <sub>C</sub>	1 W	Š					
Junction temperature	T <sub>j</sub> 150 °C							
Storage temperature	T <sub>stg</sub> –	55 to +150 °C		0				
Content $I_C$ $-2$ $A$ Marking Symbol: 11Peak collector currentIcr $-3$ $A$ Marking Symbol: 11Collector power dissipation * $P_C$ 1WJunction temperature $T_j$ 150°CStorage temperature $T_{stg}$ $-55$ to $+150$ °CNote) *: Print circuit board: Copper foil area of 1 cm <sup>2</sup> or more, and the board thickness of 1.7 mm for the collector portionThe board the board the board the board the board the board the collector portionElectrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$ The board the collector portionThe board the								
Parameter	Symbol	Conditions	Min	Тур	Max	Unit		
Collector-base voltage (Emiter open)	V <sub>CBO</sub>	$I_{\rm C} = -10 \text{ mA}$ $I_{\rm E} = 0$	-50			V		
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -1 \mathrm{mA},  I_{\rm B} = 0$	-50			V		
Emiter-base voltage (Collector open)	V <sub>EBO</sub>	$J_E = -10 \mu A$ , $P_C = 0$	-5			V		
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = -20 \text{ V}, I_E = 0$			- 0.1	μΑ		
Forward current transfer ratio *1	h <sub>FE1</sub>	$V_{CE} = -2 V, I_C = -200 mA$	120		340			
	h <sub>FE2</sub>	$V_{CE} = -2 V, I_C = -1 A$	60					
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{C} = -1 \text{ A}, I_{B} = -50 \text{ mA}$		- 0.2	- 0.3	V		
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_{\rm C} = -1$ A, $I_{\rm B} = -50$ mA		- 0.85	-1.2	V		
Transition frequency	f <sub>T</sub>	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		150		MHz		
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		45	60	pF		

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*1: Pulse measurement D --- 1- -1- -- : f: -- + :

*2: Rank classification							
Rank	R	S					
h <sub>FE1</sub>	120 to 240	170 to 340					

**Panasonic** 



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